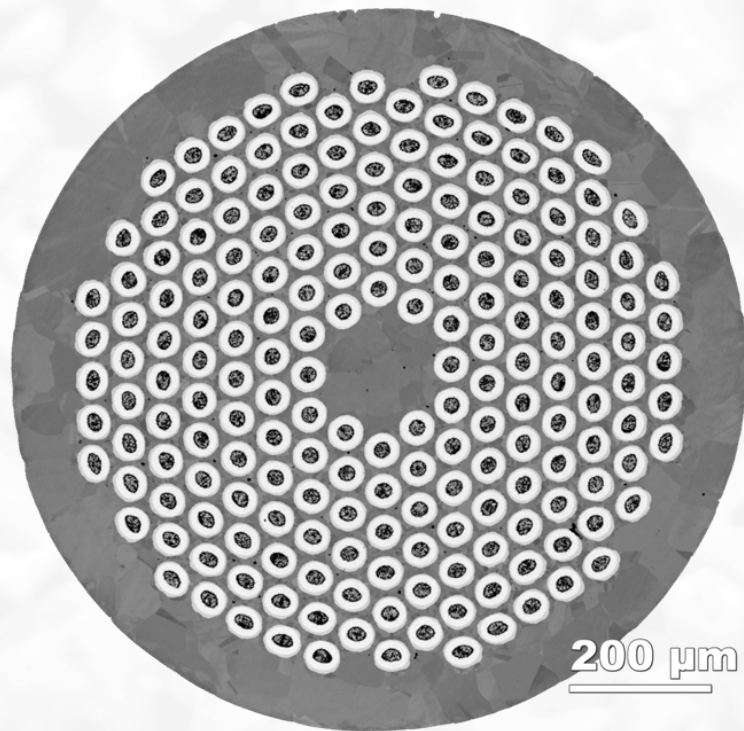


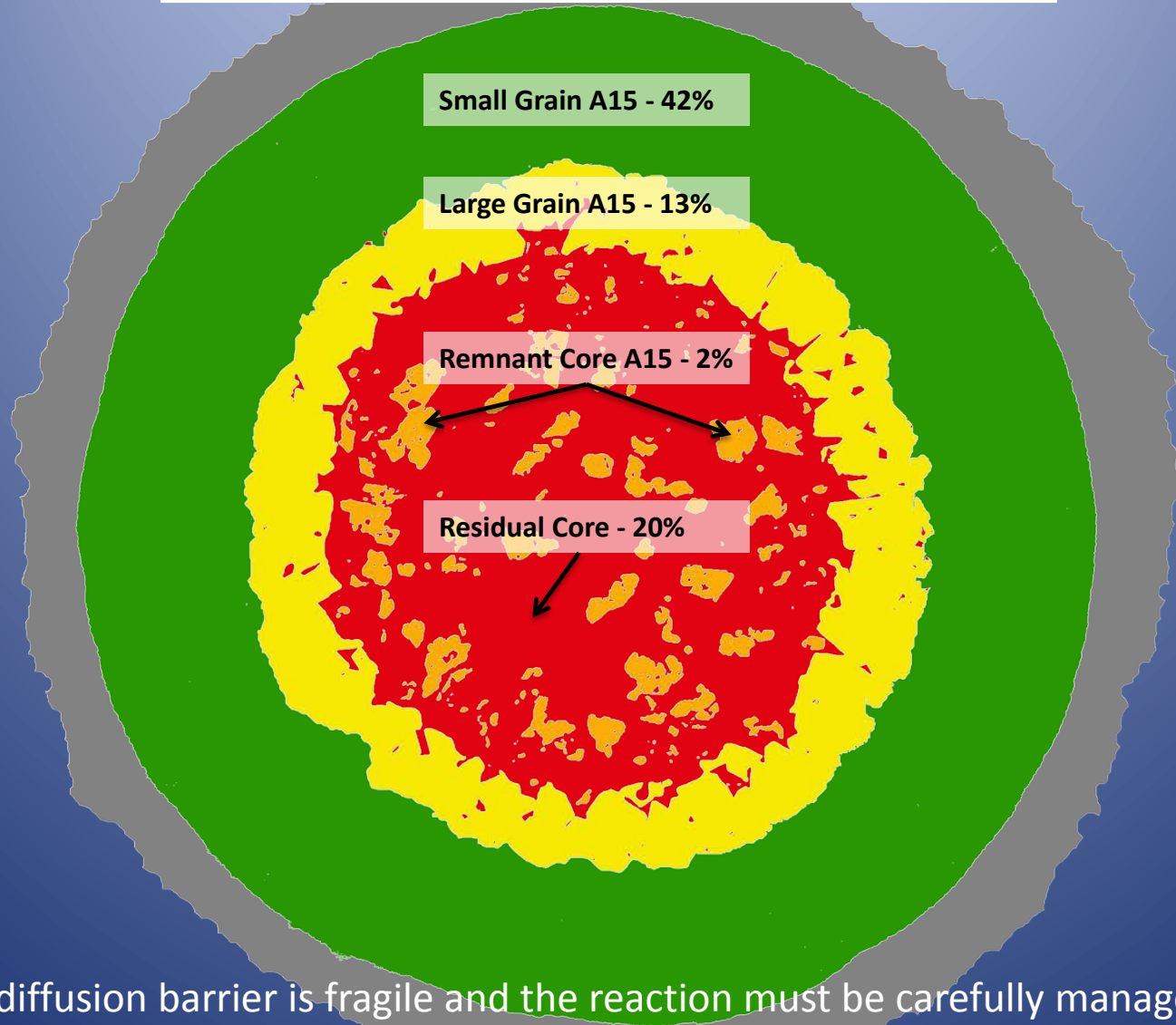
Can Higher Critical Current of Powder In Tube (PIT) Nb_3Sn be further developed without loss of RRR



Chris Segal
August 11, 2014



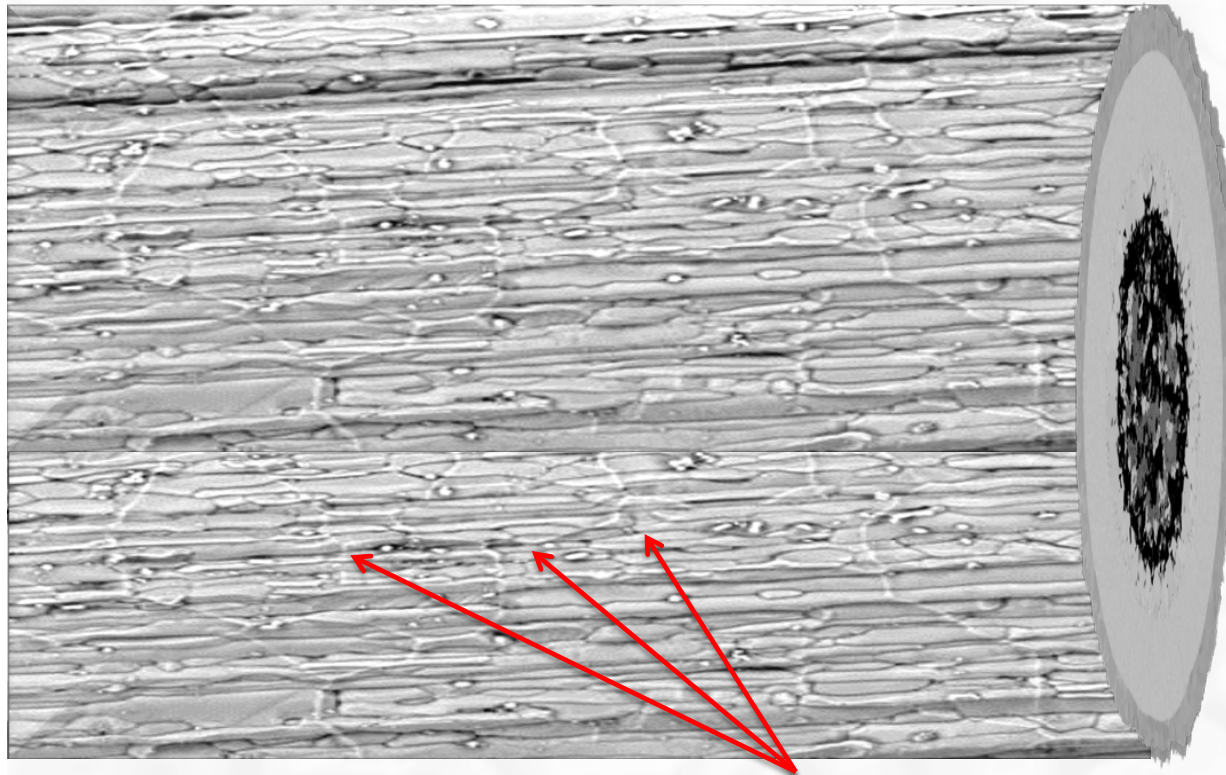
The Fractional Real Estate of PIT



- The diffusion barrier is fragile and the reaction must be carefully managed
- Only **small grain A15** carries current



Are the large grains really contributing to current carrying capability?



LG A15
appears very
disconnected

And here we can see Cu-rich phases penetrating between LG's

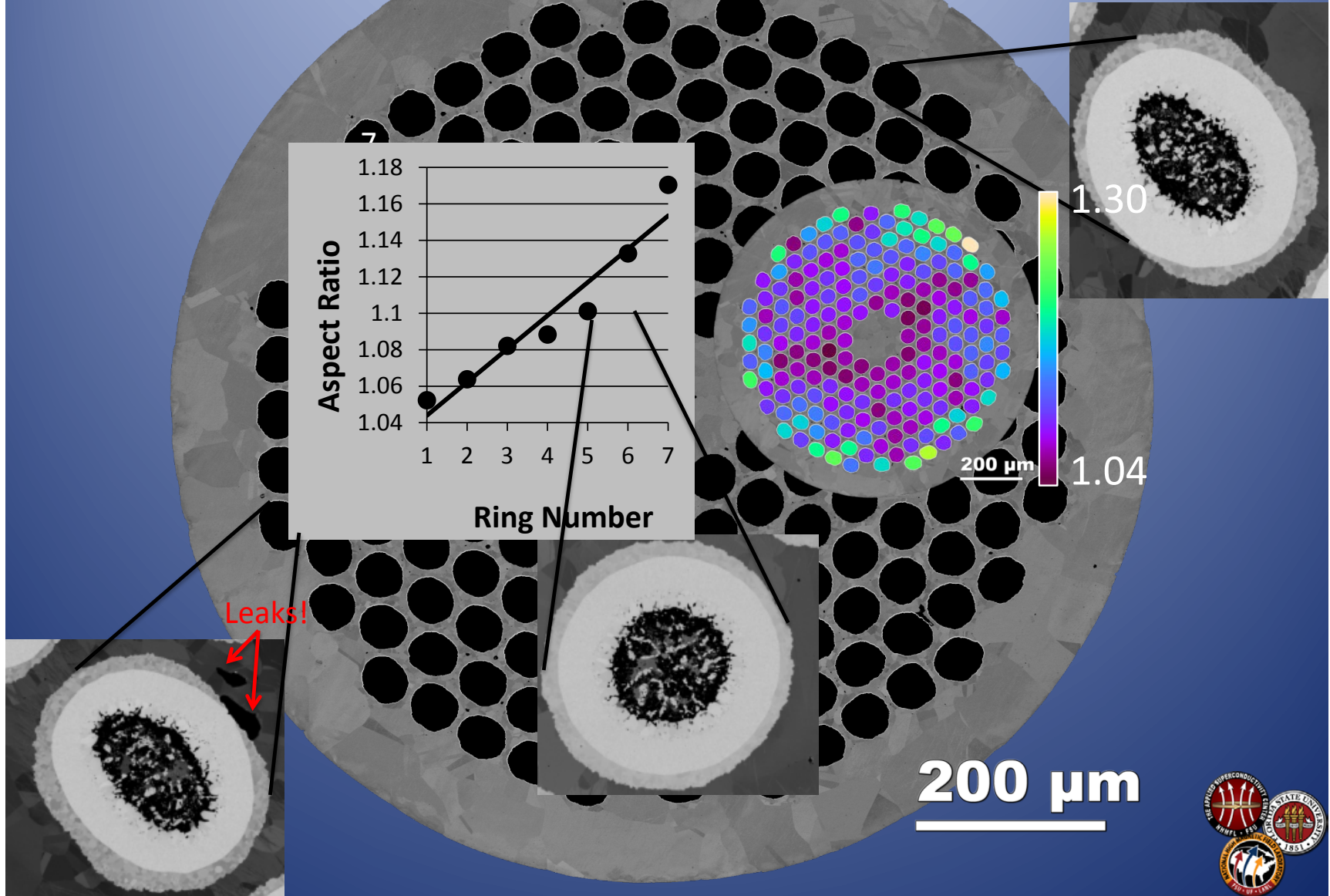


How do we make more **current carrying** superconducting A15 phase?

We must do this while maintaining...

- High Residual Resistance Ratio (RRR)
 - Keep diffusion barriers intact
- High grain boundary (GB) density
 - Produce small grains

Shape Analysis shows non-uniform deformation

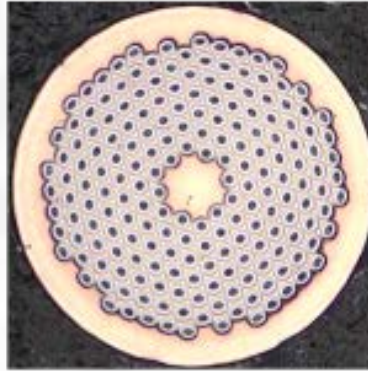




How RRR varies within filament pack

-Serial etching experiment

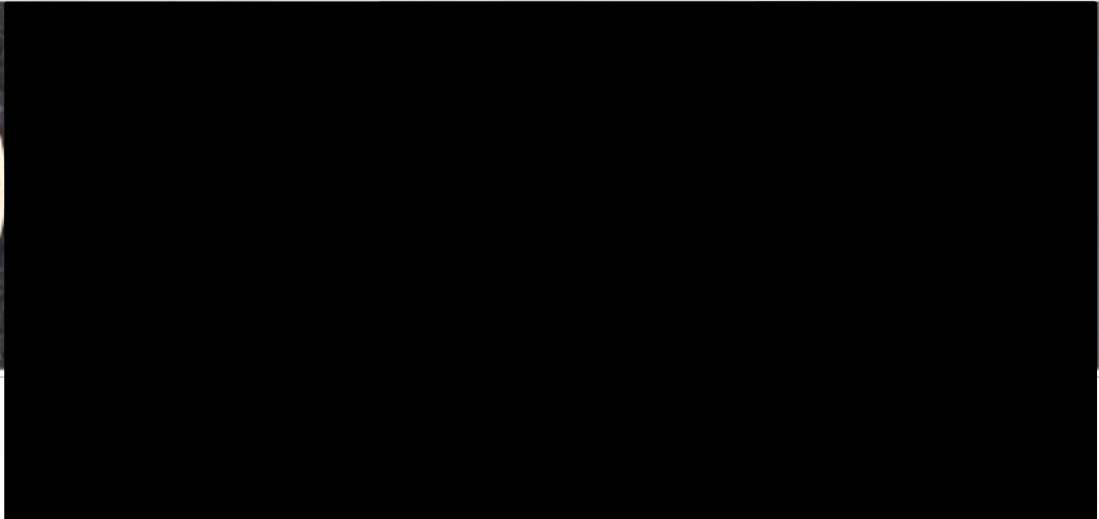
Initial sample



Etch 1

Etch 2

Etch 3

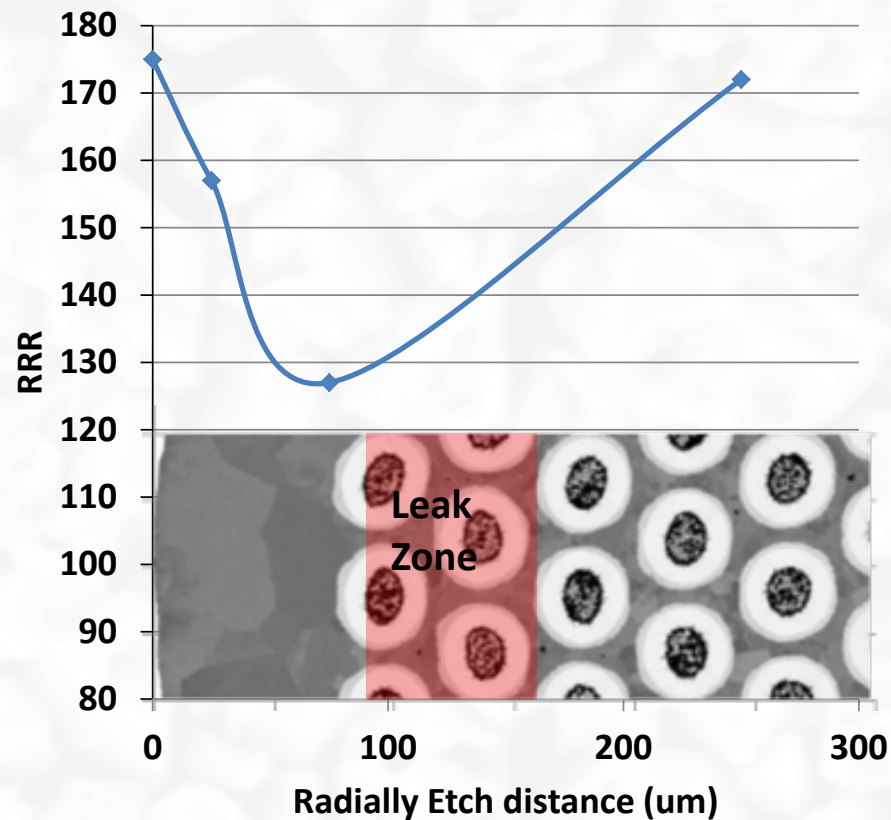


RRR

175



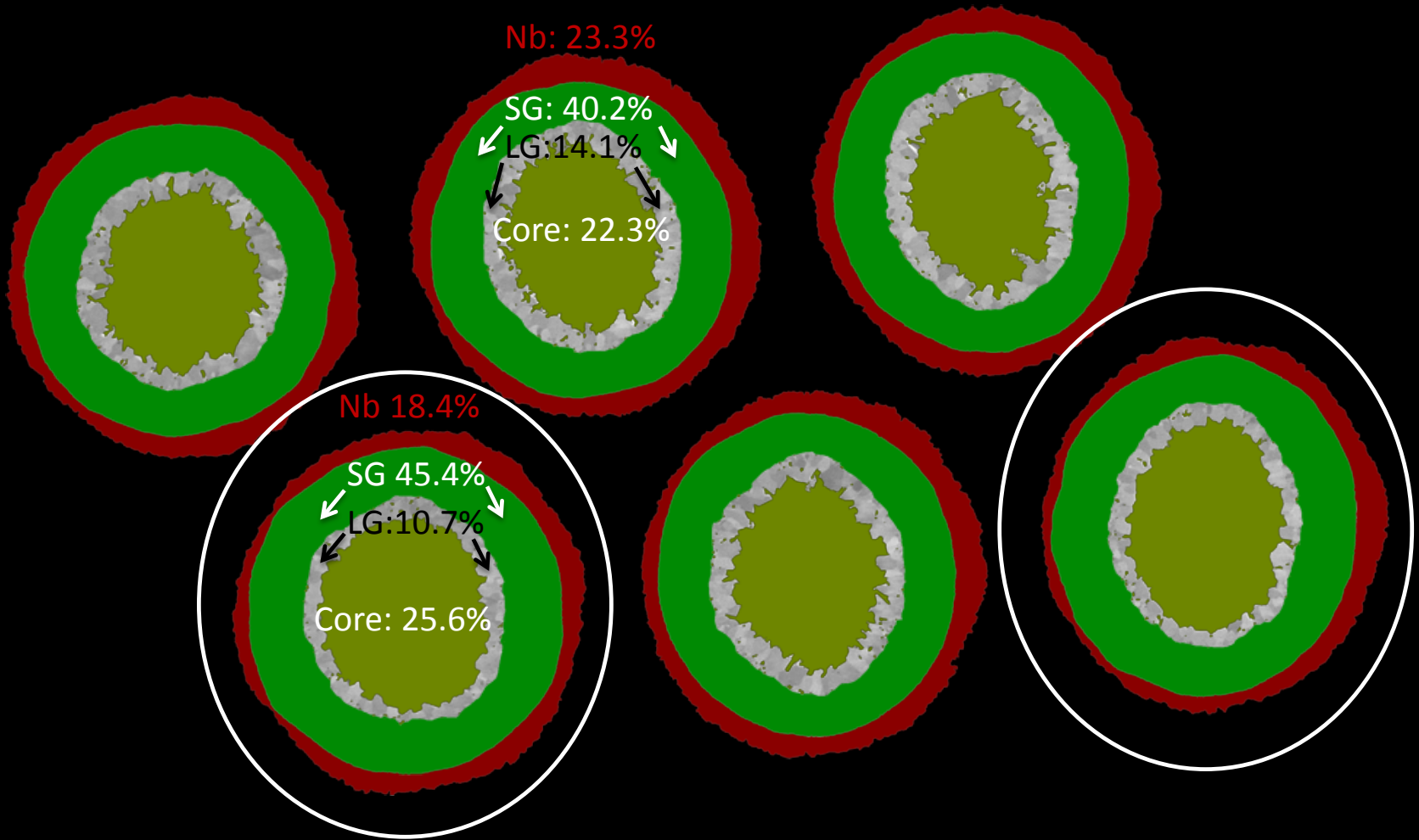
RRR varies depending on local Cu quality



There is clearly a zone more susceptible to leaks which is found in rings 6 & 7

- Longer reaction time will not help! **Where else can we make gains in J_c ?**

Two distinct filament types



650C100h B29992

Cu

Nb

Typical filament*

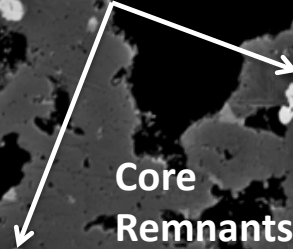
*residual Sn-rich phase in core

SG A15

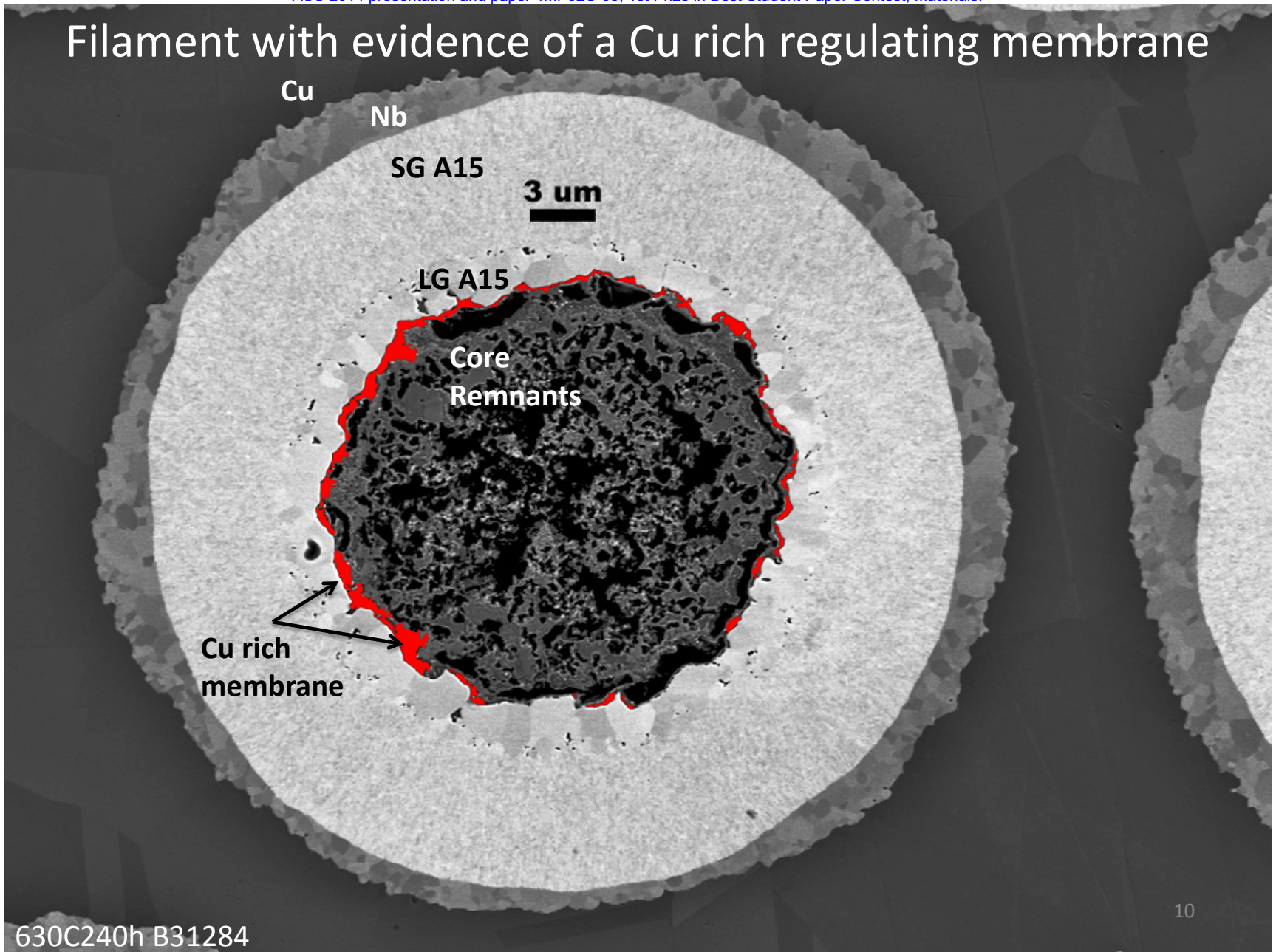
LG A15

Core A15

Core Remnants

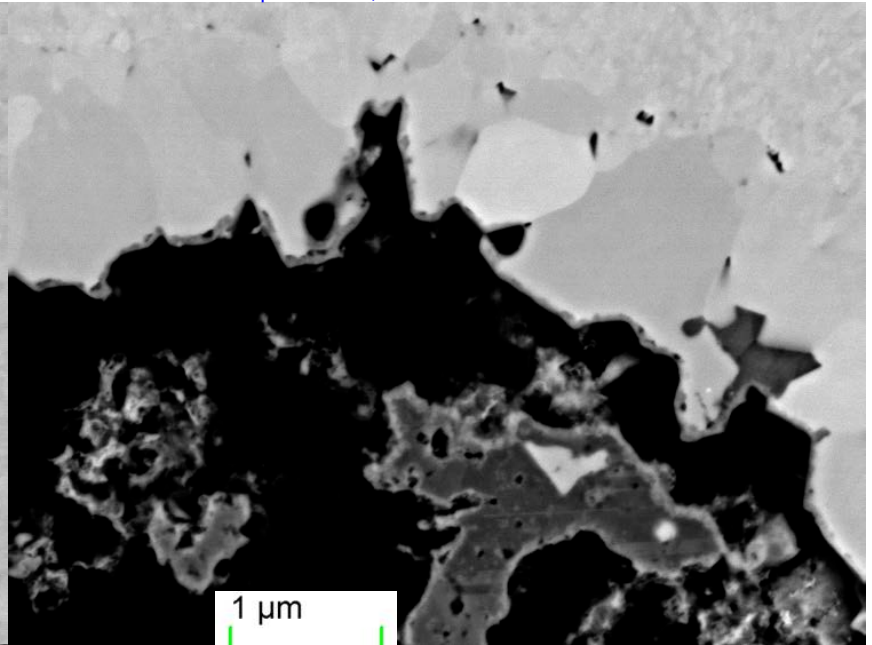
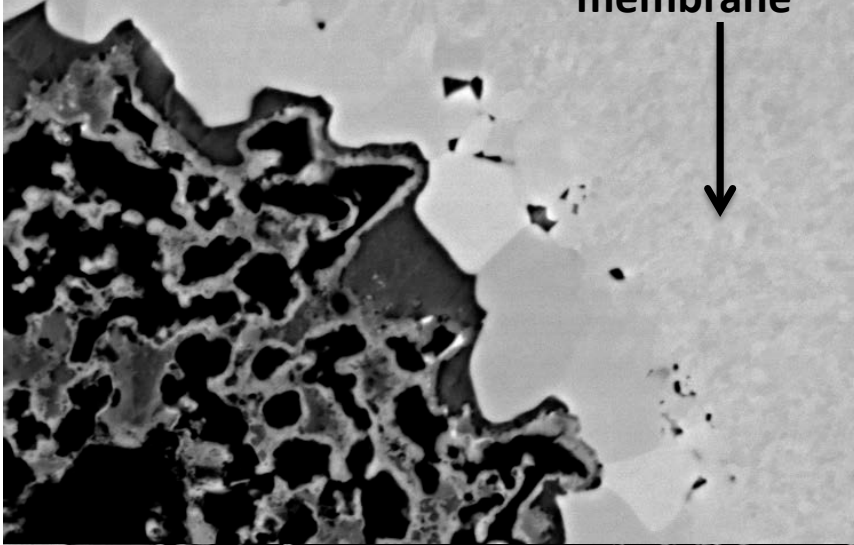


Filament with evidence of a Cu rich regulating membrane

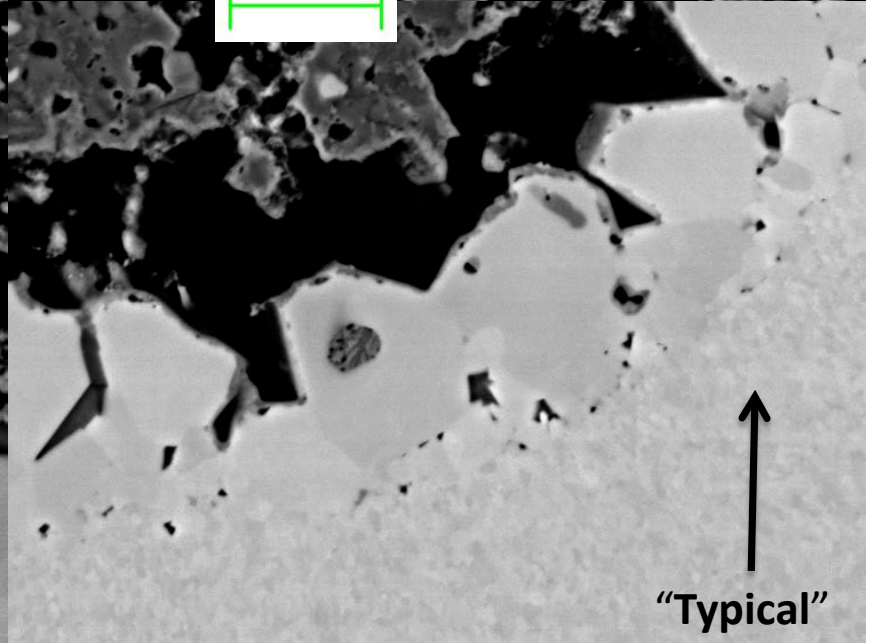
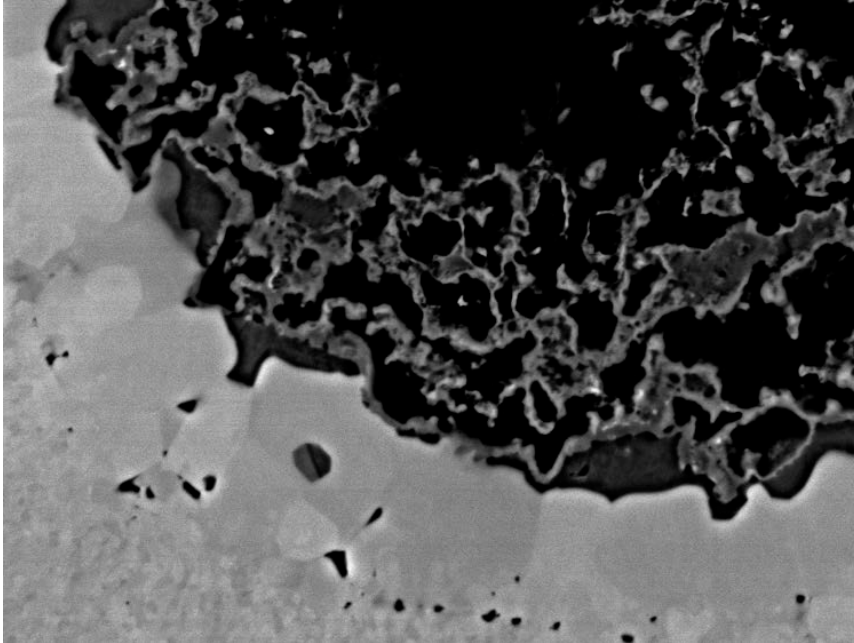




atypical with
membrane

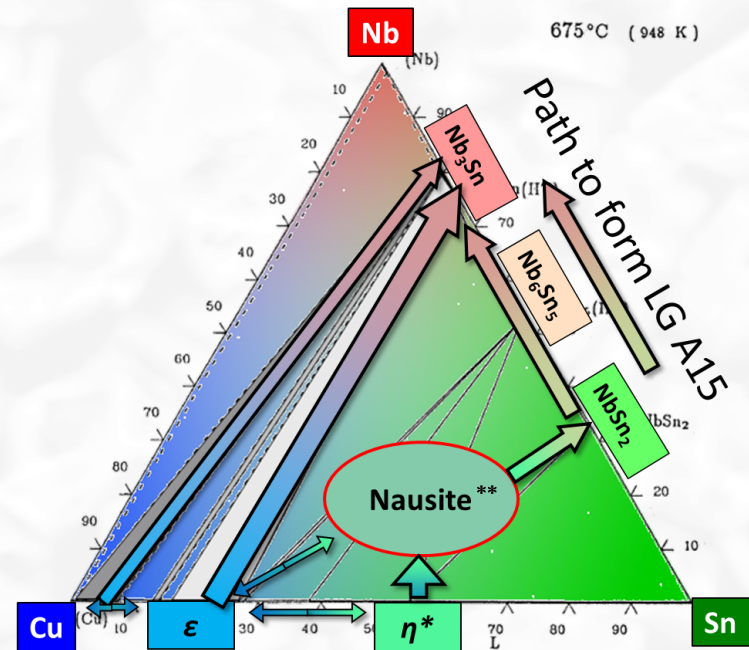
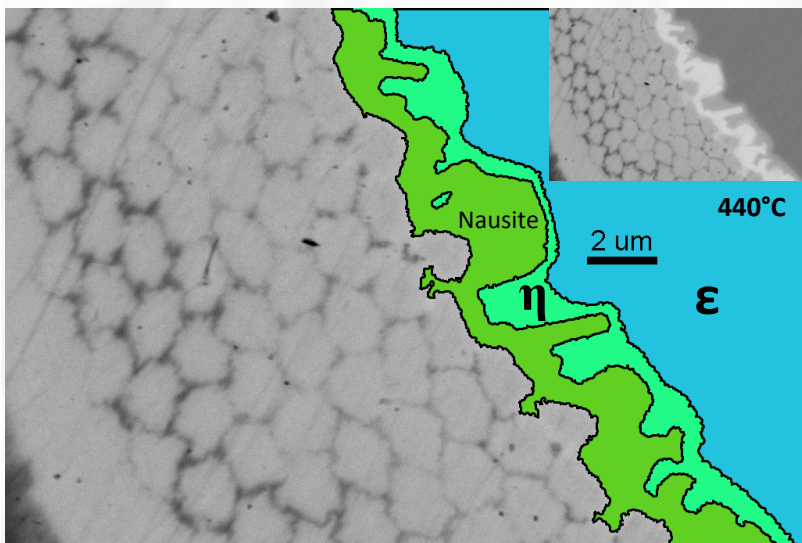


1 μm



↑
"Typical"

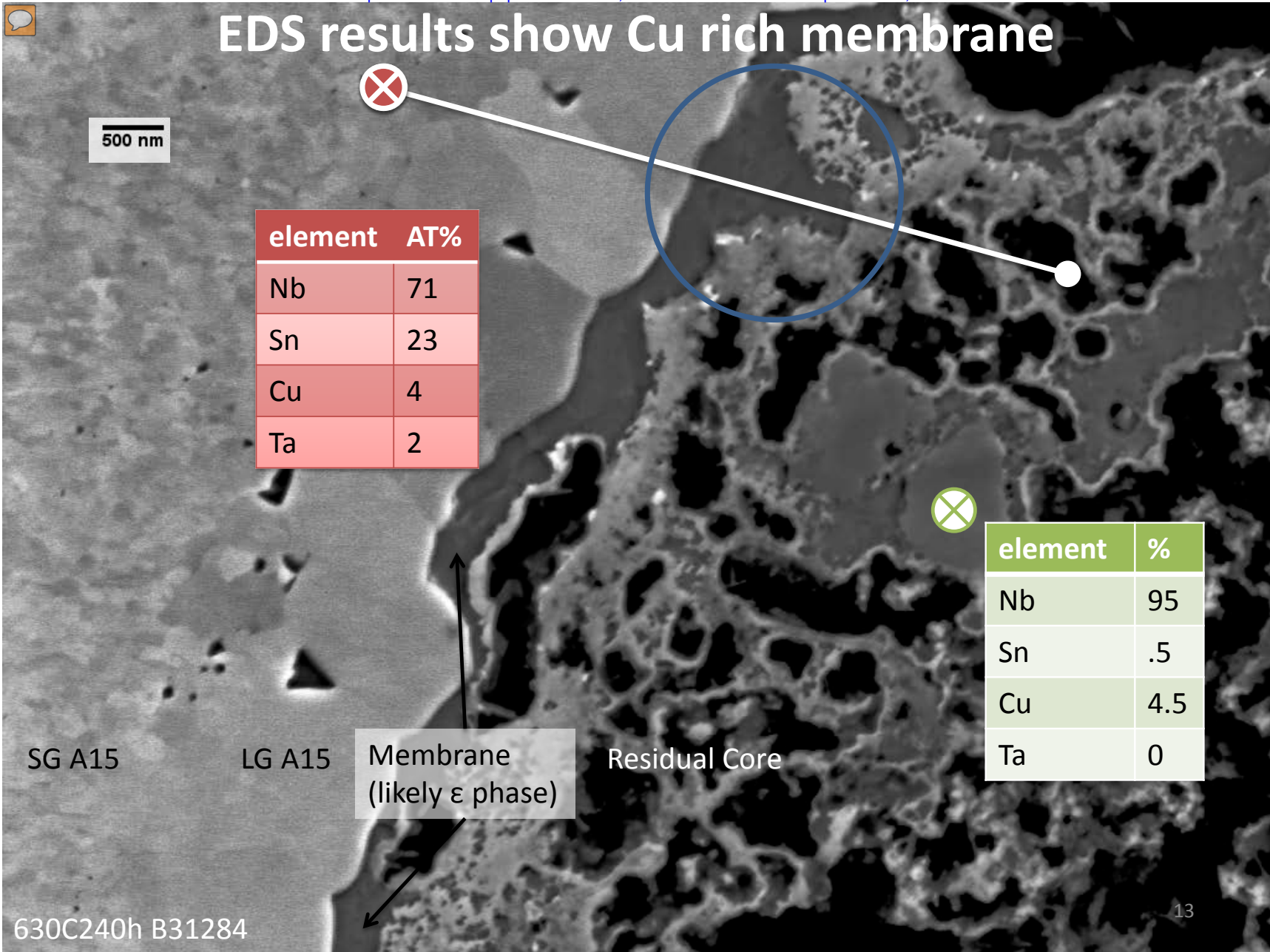
An intermediate Cu-Nb-Sn phase (Nausite) forms in internal tin strands^[1]



Phase illustration by C. Sanabria

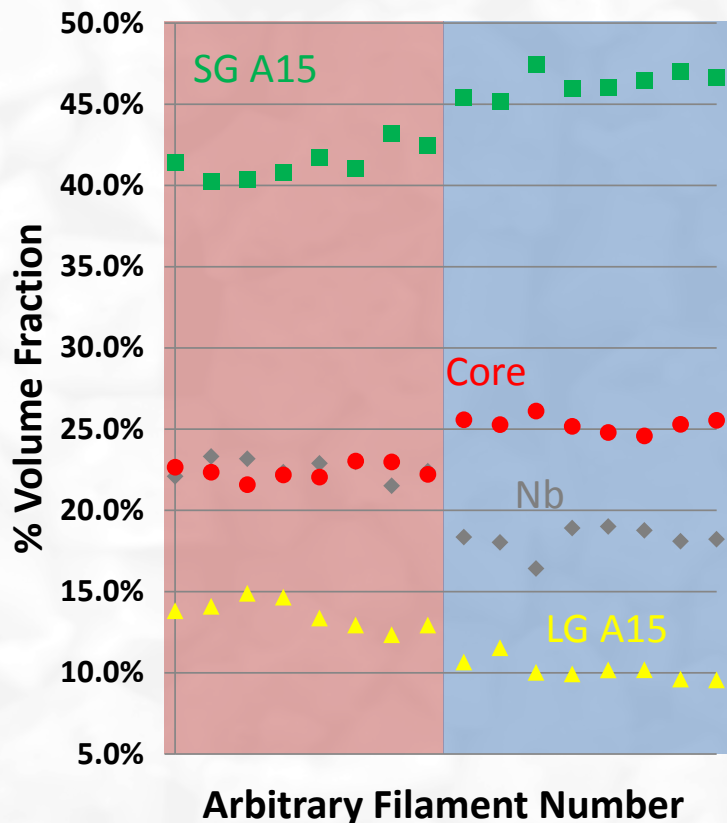
[1] I. Pong, L.-R. Oberli, and L. Bottura, "Cu diffusion in Nb₃Sn internal tin superconductors during heat treatment," *Supercond. Sci. Technol.*, vol. 26, no. 10, p. 105002, Oct. 2013.

EDS results show Cu rich membrane



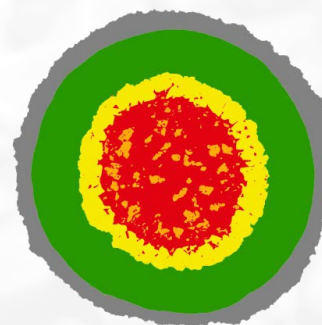


Comparison of **typical** and **atypical** filaments



element	AT%
Nb	22.6
SG A15	41.4
LG A15	13.6
Core	22.4

element	AT%
Nb	18.2
SG A15	46.3
LG A15	10.2
Core	25.3



element	% change
Nb	-20
SG A15	+12
LG A15	-25
Core	+13

12% increase in the good stuff!

Comparison of end phase fractions of PIT and RRP

Condition and Component %	54/61 RRP® (Tarantini SuST 2014)	PIT 192 (CS evaln 2013)	PIT 192 (CS evaln 2014 –atypical filaments)
HT	620C, 192h	650°C, 100 h	630°C, 240 h
RRR	377	177	177
A15 total %	58.8	56	56.7
A15 SG %	58.8	40	46
A15 LG %		16	10.7
Residual DB %	8.1	24.5	17.6
Residual core %	33.1	19.5	25.7

* = 169 and 217 RRP® stacks need ~10% residual DB

Increase in SG A15 without loss of RRR!

Findings for discussion

- A Cu rich membrane to mediate the reaction appears VERY useful
 - Why does this membrane form and why does it positively affect A15 growth?
- The issue – better control the reaction path:
 - **Can we avoid large grain A15?**
 - Consume all present Sn in package to produce current carrying SG A15
- The payoff?
 - Typical filaments have a 3:1 SG:LG ratio
 - Untypical filaments have a 4:1 SG:LG ratio!
 - Even more valuable, the total amount of SG A15 is enhanced from an average of 41% to 46%, a 12% increase – surely beneficial for J_c

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